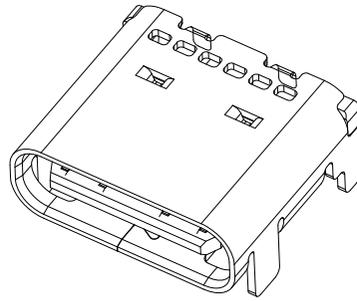
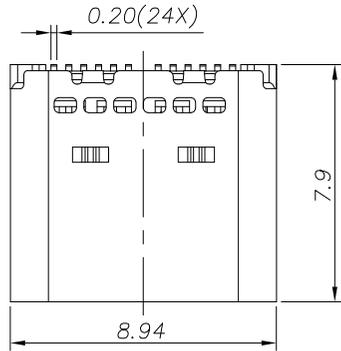


GP Component

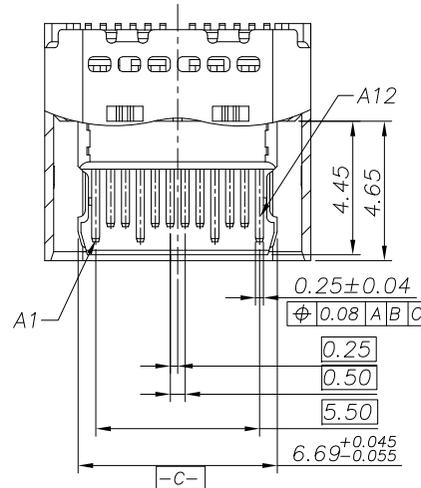
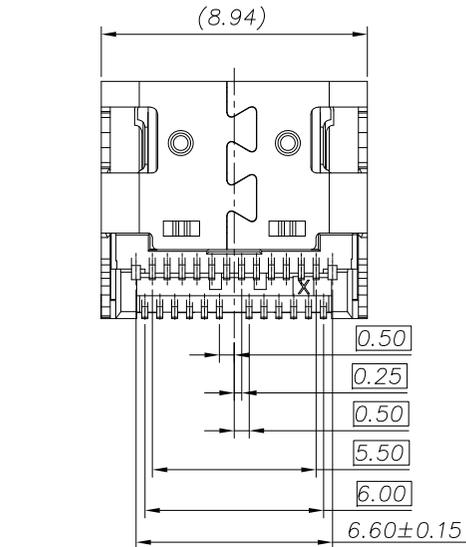
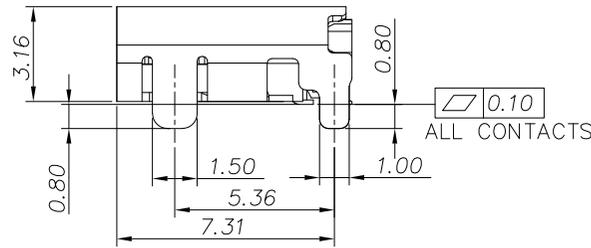
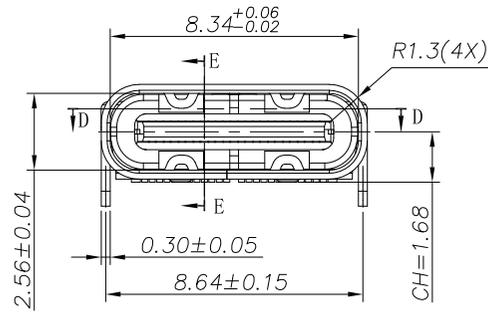
| REV. | ECN NO. | LOCATIONS | DESCRIPTION | DATE | DESIGN |
|------|---------|-----------|-------------|------------|---------|
| A0 | | | Initial | 2023/08/09 | Ken Lin |



3D View

NOTE:

- MATERIAL SPECIFICATION:
 - HOUSING: PA9T GP2300F, UL94 V-0, BLACK.
 - CONTACTS: COPPER ALLOY
 - EMI PLATE: STAINLESS STEEL
 - FRONT SHELL: STAINLESS STEEL
 - MID PLATE: STAINLESS STEEL
- PLATING SPECIFICATION:
 - CONTACTS:
 - Ni 50u" MIN. UNDER PLATED OVER ALL.
 - Au PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW THE P/N)
 - PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - FRONT SHELL:
 - Ni 30u" MIN. UNDER PLATED OVER ALL.
 - MID PLATE:
 - Ni 30u" MIN. UNDER PLATED OVER ALL.
 - Sn 80u" MIN. PLATED OVER ALL
 - EMI PLATE:
 - CLEAR ONLY
- MECHANICAL PERFORMANCE,
 - INSERTION FORCE: 0.5~2.0kgf.
 - REMOVAL FORCE: 0.8kgf~2.0kgf.
 - DURABILITY: 10000 CYCLES.
- ELECTRICAL PERFORMANCE,
 - CURRENT RATING: 5.0A
VOLTAGE RATING: 5.0V
 - LLCR:
 - VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.
 - SHIELD: 50mΩ/MAX.
 - LLCR MAX. CHANGE OF ALL PINS: 10mΩ
 - INSULATION RESISTANCE: 100MΩ MIN
 - DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.
- ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -40°C~+85°C.
- IR REFLOW:
 - THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.



SECTION: D-D
SCALE: 1:1

MATRIX PART NO:

MUSB12 - 01 - 827

MATRIX TYPE-C

Series number

Gold Plating
01: Gold Flash (1u")
30: 30u"

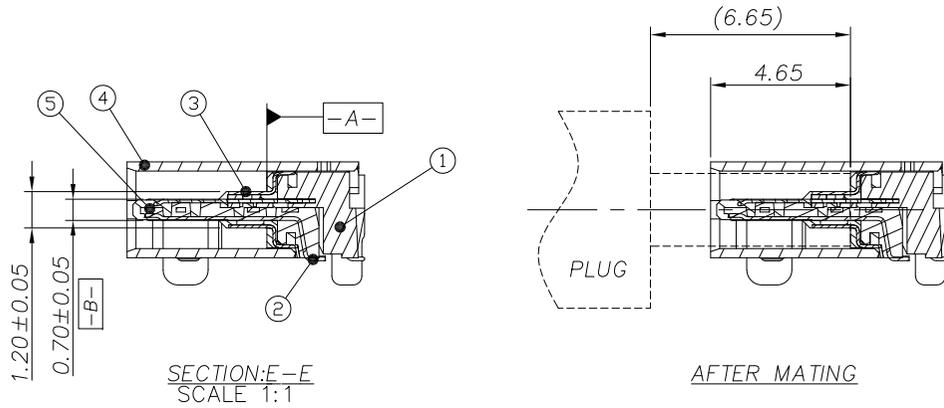


Matrix Electronics Co.,Ltd

| | | | | |
|---|--------------------------------|----------------------|--|---------------|
| TOLERANCE: X.X ±0.50 X.XX ±0.38 X.XXX ±0.25 X.XXX ±0.15 ANGLE: ±3° | DESIGN BY : Ken Lin | DATE : 2023/08/09 | PART NAME: USB 3.2 Gen2 TYPE-C 母座/板上式, 24PIN双排贴SMT | |
| UNIT: mm [inch] | CHECKED BY: Hanson Huang | DATE : 2023/08/09 | PART NO. | MUSB12-01-827 |
| SCALE: 1:1 SIZE: A4 | APPROVED BY1: Richard Hsieh | DATE : 2023/08/09 | MOLD NO. | NA |
| | APPROVED BY2: Richard Hsieh | DATE : 2023/08/09 | DRAW NO. | |
| | | | SHEET NO. | 1 OF 2 |

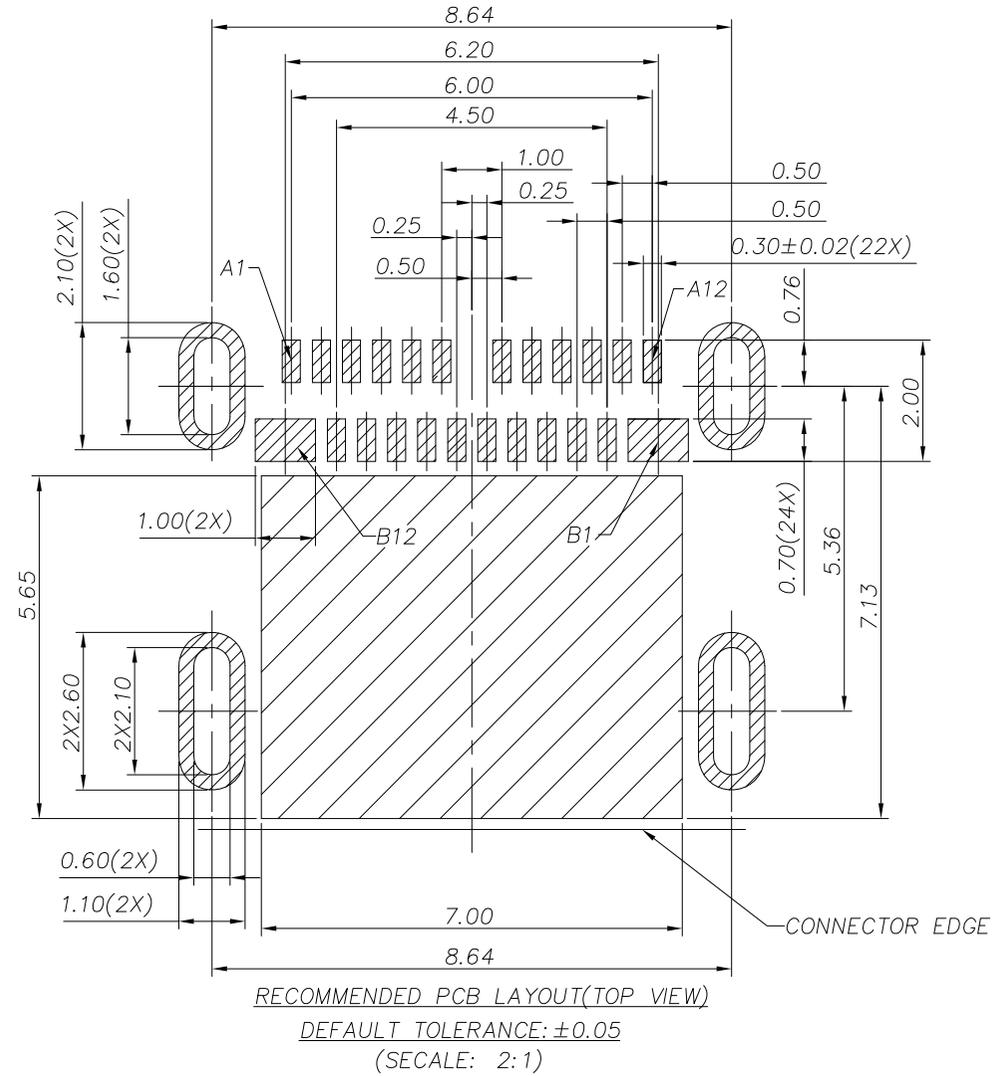
GP Component

| REV. | ECN NO. | LOCATIONS | DESCRIPTION | DATE | DESIGN |
|------|---------|-----------|-------------|------------|---------|
| A0 | | | Initial | 2023/08/09 | Ken Lin |



USB TYPE-C PIN ASSIGNMENTS

| PIN NUMBER | SIGNAL NAME | PIN NUMBER | SIGNAL NAME |
|------------|-------------|------------|-------------|
| A1 | GND | B12 | GND |
| A2 | SSTXp1 | B11 | SSRXp1 |
| A3 | SSTXn1 | B10 | SSRXn1 |
| A4 | Vbus | B9 | Vbus |
| A5 | CC1 | B8 | SBU2 |
| A6 | Dp1 | B7 | Dn2 |
| A7 | Dn1 | B6 | Dp2 |
| A8 | SBU1 | B5 | CC2 |
| A9 | Vbus | B4 | Vbus |
| A10 | SSRXn2 | B3 | SSTXn2 |
| A11 | SSRXp2 | B2 | SSTXp2 |
| A12 | GND | B1 | GND |



Matrix Electronics Co., Ltd

| | | | | |
|--|--------------------------------|----------------------|--|---------------|
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| | CHECKED BY: Hanson Huang | DATE : 2023/08/09 | PART NO. | MUSB12-01-827 |
| UNIT: mm [inch] SCALE: 1:1 SIZE: A4 | APPROVED BY1: Richard Hsieh | DATE : 2023/08/09 | MOLD NO. | NA |
| | APPROVED BY2: Richard Hsieh | DATE : 2023/08/09 | DRAW NO. | |
| | | | SHEET NO. | 2 OF 2 |